



Attorney Docket SEL 189

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of)
Takayama et al.)
Serial No.: 09/598,736)
Filed: June 21, 2000)
For: Wiring Material, Semiconductor Device)
Provided With A Wiring Using The Wiring)
Material And Method Of Manufacturing Thereof)
Art Unit: 2811)
Examiner: H. Vu)
Commissioner for Patents
Washington, D.C. 20231

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14/B
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January 17, 2003

AMENDMENT B

Sir:

In response to the Final Rejection of July 18, 2002, a RCE and three month extension of time
being submitted herewith, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice Amended) A semiconductor device comprising:
a wiring formed over a substrate, the wiring comprising a tungsten nitride film and a
tungsten film formed thereon,
wherein the wiring include at least one inert element, and 90% or more of the inert
element is argon, and

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